

NOTES

1. 嵌合相手: 501189-****
MATE WITH: 501189-****
2. ソルダピン及びネールの平坦度は0.1MAX.
SOLDER PIN AND NAIL COPLANRITY TO BE 0.1MAX.
3. 極数/2=偶数極の場合に適用
APPLY FOR (CIRCUIT/2=EVEN)
4. 製品番号
MATERIAL No.
501571 - **07 , 501571 - **5*

極数	↑	極数	↑	色
CIRCUIT SIZE		CIRCUIT SIZE		COLOR
5. トレードマーク: MXプラス1文字のアルファベットにて構成
キャビティー番号: 1桁から2桁の数字にて構成
金型番号: アルファベット1文字にて構成
TRADE MARK: FORMED BY MX AND 1 MORE
LETTER OF ALPHABET, BUT "J" MEANS JAPAN. (e.g. MXJ)
CAVITY No.: FORMED BY 1 - 2 DIGIT NUMBERS.
MOLD No.: FORMED BY 1 LETTER OF ALPHABET.
6. ELV 及び RoHS 適合品
ELV AND RoHS COMPLIANT.

SECTION C-C

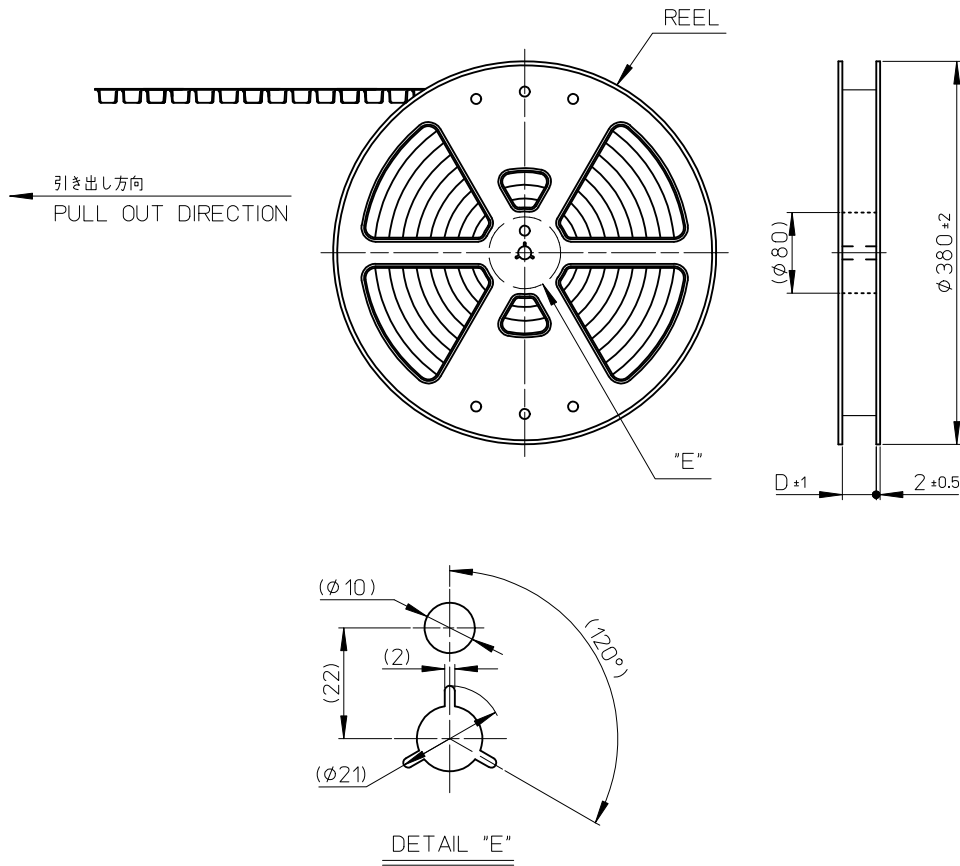
24	28	501571-50**	50
19	23	501571-40**	40
14	18	501571-30**	30
9	13	501571-20**	20
B	A	EMBOSSED PACKAGE	CKT
		オーダー番号 ORDER NO.	
CONNECTOR SERIES No. 501571-****			

番号 NO.	部品 PART	材質 MATERIAL
①	ウエハー WAFER	耐熱ナイロン、UL94V-0、色: シート2参照 HEAT RESISTANCE NYLON, UL94V-0, COLOR:SEE SHEET2
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 金メッキ : 0.1 MICRO METER MINIMUM. GOLD PLATING ニッケル下地メッキ : 1 MICRO METER MINIMUM. NICKEL UNDER PLATING
③	ネイル NAIL	黄銅 BRASS すずメッキ : 1 MICRO METER MINIMUM. TIN PLATING ニッケル下地メッキ : 1 MICRO METER MINIMUM. NICKEL UNDER PLATING

REVISED EC NO: J2012-0269 IDRW:KAWASHIO 2011/08/24 CHYD:KASAKAWA 2011/08/26 APPR:NUKITA 2011/08/26	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	REV	10 UNDER ±0.2	DRAWN BY TRSUZUKI	DATE 2005/02/14	TITLE 1.0 WIRE TO BOARD CONN. 2-ROW R/A WAFER ASSY -LEAD FREE-		
		10 OVER 30 UNDER ±0.25	CHECKED BY MYAGI	DATE 2005/02/14	MOLEX MOLEX INCORPORATED		
		30 OVER ±0.3	APPROVED BY ANODA	DATE 2005/02/14	DOCUMENT NO. SD-501571-001	SHEET NO. 1 OF 2	
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

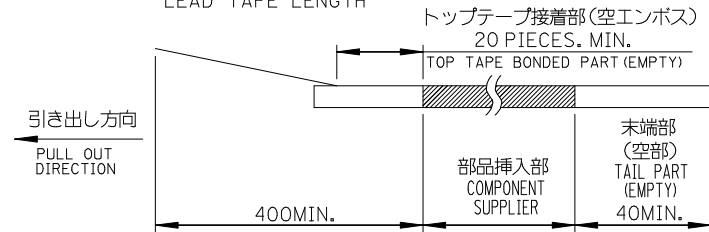
緑 GREEN		青 BLUE		赤 RED		黒 BLACK		自然色 NATURAL		色 COLOR
//	501571-***76	//	501571-***74	//	501571-***72	//	501571-***71	501571-5007	501571-***09	50
//		//		//		//		501571-4007		40
501571-3056		501571-3054		501571-3052		501571-3051		501571-3007		30
501571-2056	501571-2054	501571-2052	501571-2051	501571-2007	20					
EMBOSSED PACKAGE オーダー番号 ORDER NO.	CONNECTOR SERIES	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CONNECTOR SERIES	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CONNECTOR SERIES	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CONNECTOR SERIES	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CONNECTOR SERIES	CKT.

SEE SHEET 1 EC NO.: J2012-0269 DRWN: KAWASHIO 2011/08/24 CHKD: KASAKAWA 2011/08/26 APPR: NUKITA 2011/08/26	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY TRSUZUKI	DATE 2005/02/14	TITLE 1.0 WIRE TO BOARD CONN. 2-ROW R/A WAFER ASSY -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/02/14	APPROVED BY ANODA 2005/02/14				
		30 OVER	±0.3	ANGULAR ±3 °		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-501571-001		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

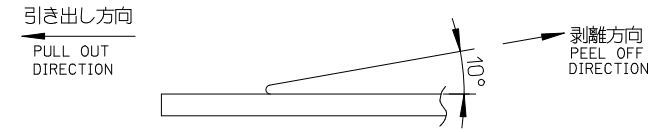


NOTES

- 製品詳細寸法については SD-501571-001 を参照ください。
RE DETAILED DIMENSION, SEE SD-501571-001
- 梱包数量： 800 個/リール
NUMBER OF CONNECTORS : 800 PIECES/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- トップテープの剥離強度：0.1~1.3N(10.2 ~ 132.5gf) (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE (PEELING DIRECTION AS SHOWN IN FOLLOWING FIGURE)
尚、本規格値は、出荷時に適用。(但し、輸送時に剥離が発生しないこと)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTION.



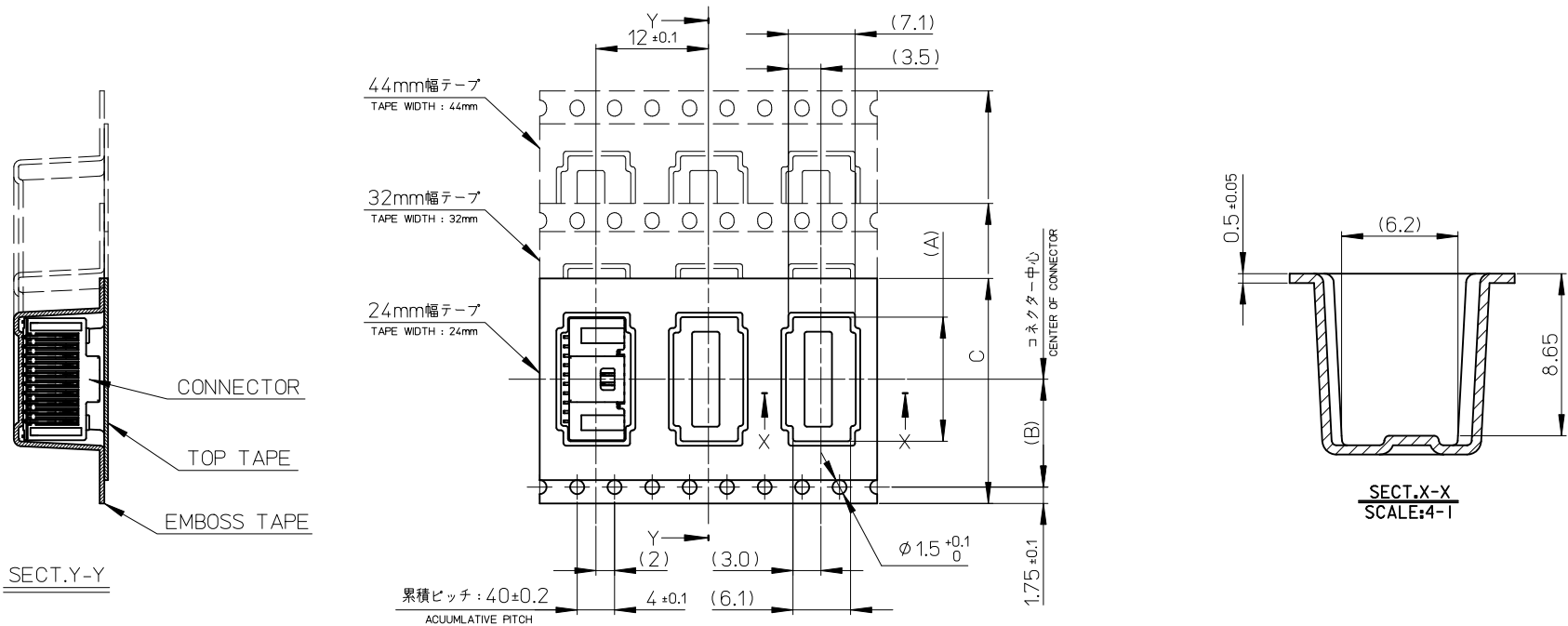
- 材料
MATERIAL
キャリアテープ：ポリプロピレン
CARRIER TAPE: POLYPROPYLENE
トップテープ：PET, PE, REF
TOP TAPE
リール：ポリスチレン (リサイクル材を含む)
REEL : POLYSTYRENE (RECYCLE MATERIAL CONTAINED)

- 乾燥剤入り防湿梱包仕様になります。(501571-**07以外)
INCLUDING DESICCANT TAPING PACKAGE.
(BESIDES 501571-**07)

- ELV 及び RoHS 適合品
ELV AND RoHS COMPLIANT.

REVISED EC NO: J2012-0269 DRWN:KASHIO 2011/08/24 CHKD:KASAKAWA 2011/08/26 APPR:NUKITA 2011/08/26	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY TRSUZUKI	DATE 2005/02/14	TITLE 1.0 WIRE TO BOARD CONN. 2-ROW R/A WAFER ASSY EMBTP PKG -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/02/14	MOLEX INCORPORATED				
		30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/02/14	MATERIAL NO. SEE SHEET 2	DOCUMENT NO. SD-501571-002	SHEET NO. 1 OF 3		
REV		ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

引き出し方向
PULL OUT DIRECTION



45.5	44±0.3	20.2	28.3	501571-5009	501571-5007	50
			23.3	501571-4009	501571-4007	40
33.5	32±0.3	14.2	18.3	501571-3009	501571-3007	30
				501571-307*	501571-305*	
25.5	24±0.3	11.5	13.3	501571-2009	501571-2007	20
				501571-207*	501571-205*	
D	C	(B)	(A)	CONNECTOR SERIES NO.	EMBOSSED PACKAGE ORDER NO.	CKTS.

SEE SHEET 1 EC NO: J2012-0269 DRW:KAWASHIO 2011/08/24 CHK:D:KASAKAWA 2011/08/26 APPR:NUKITA 2011/08/26	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY TRSUZUKI	DATE 2005/02/14	TITLE 1.0 WIRE TO BOARD CONN. 2-ROW R/A WAFER ASSY EMBTB PKG -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/02/14	MOLEX INCORPORATED DOCUMENT NO. SD-501571-002 SHEET NO. 2 OF 3		
	30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/02/14			
ANGULAR ±3 °		MATERIAL NO. SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3					

緑 GREEN	青 BLUE	赤 RED	黒 BLACK	色 COLOR	
---	---	---	---	50	501571-**7*
---	---	---	---	40	
501571-3056	501571-3054	501571-3052	501571-3051	30	
501571-2056	501571-2054	501571-2052	501571-2051	20	
EMBOSSED PACKAGE オーダー番号 ORDER NO.				CKT.	CONNECTOR SERIES NO.

自然色 NATURAL		色 COLOR	
501571-5007	50	501571-**09	
501571-4007	40		
501571-3007	30		
501571-2007	20		
EMBOSSED PACKAGE オーダー番号 ORDER NO.		CKT.	CONNECTOR SERIES NO.

SEE SHEET 1 EC NO: J2012-0269 DRWN:KASHIO 2011/08/24 CHKD:KASAKAWA 2011/08/26 APPR:NUKITA 2011/08/26 REV:	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
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	10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/02/14	APPROVED BY ANODA 2005/02/14		
	30 OVER	±0.3	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-501571-002		SHEET NO. 3 OF 3
	ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			